

RoHS

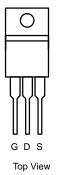
COMPLIANT

### L3402-VB Datasheet

### N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
20	$0.004@V_{GS} = 4.5V$	100		
	$0.005@V_{GS} = 2.5V$	95		



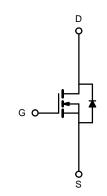


### **FEATURES**

- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
  Compliant to RoHS Directive 2011/65/EU

#### **APPLICATIONS**

- OR-ing
- Server ٠
- DC/DC ٠



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25°C UNLESS OTHERWISE NOTED)					
Paramete	r	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	v	
Gate-Source Voltage		V <sub>GS</sub>	±12	V	
Continuous Drain Current (T <sub>1</sub> = 175°C)	$T_{C} = 25^{\circ}C$	I-	100		
	T <sub>C</sub> = 100°C		85	A	
Pulsed Drain Current		I <sub>DM</sub>	260		
Avalanche Current		I <sub>AR</sub>	35		
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	45	mJ	
Power Dissipation	$T_{C} = 25^{\circ}C$	P <sub>D</sub>	125 <sup>a</sup>	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
lunction to Ambient	PCB Mount (TO-263) <sup>c</sup>	D	40		
Junction-to-Ambient	Free Air (TO-220AB)	R <sub>thJA</sub>	62.5	°C/W	
Junction-to-Case		R <sub>thJC</sub>	1.25		

Notes:

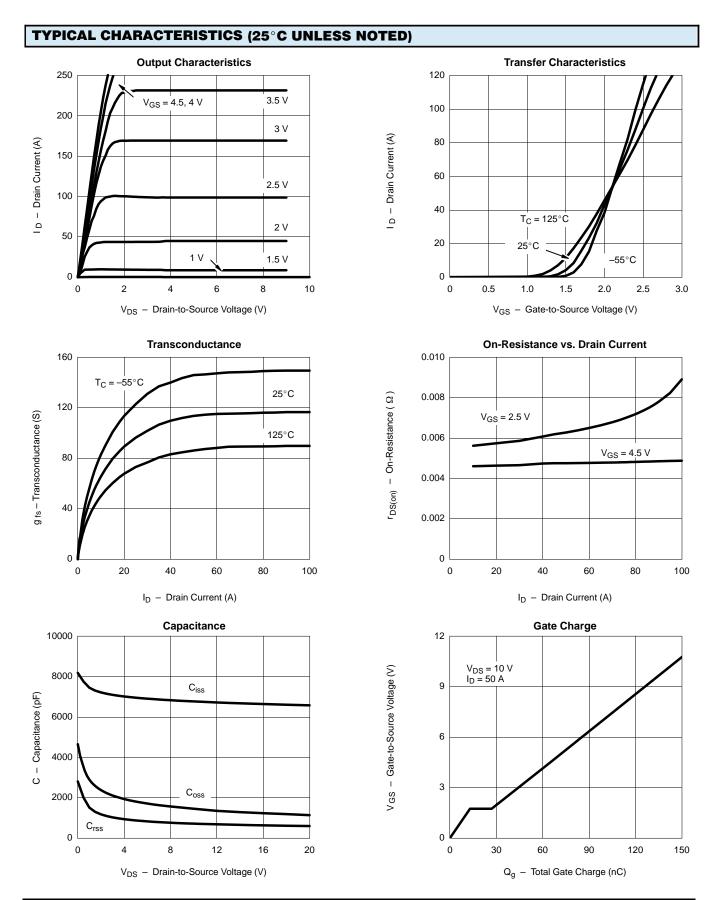
a. See SOA curve for voltage derating.

b. Duty cycle  $\leq$  1%. c. When mounted on 1" square PCB (FR-4 material).

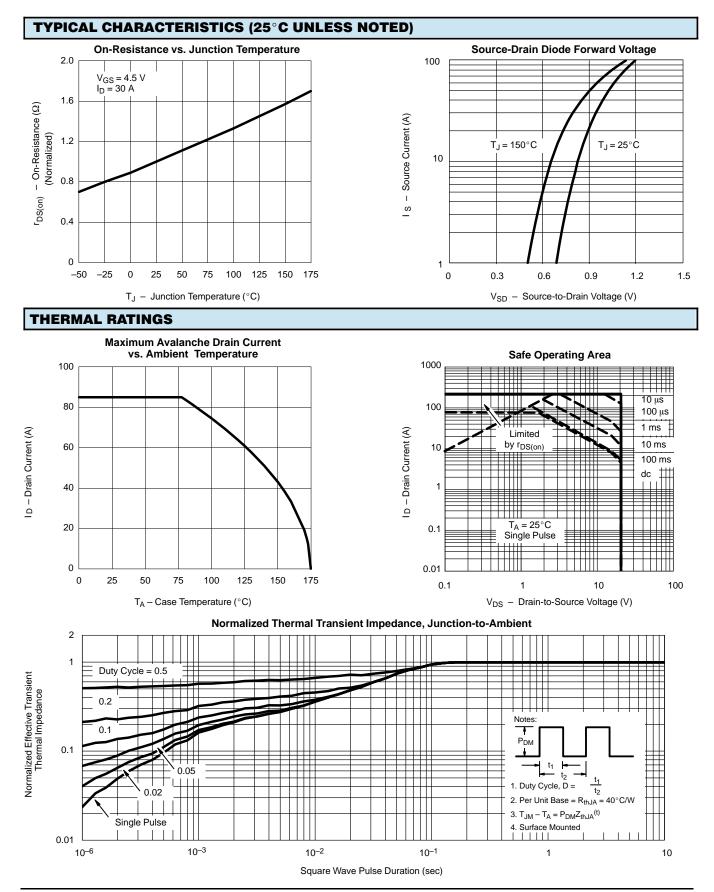


Doromotor	Symbol	Test Condition	Min	Turn	Max	11:01:4	
Parameter	Symbol	lest Condition	Min	Тур	Мах	Unit	
Static				-			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}=0 \ V, \ I_D=250 \ \mu A$	20			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{DS} = 250 \ \mu A$	0.5		1.5	, v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = $\pm$ 12 V			±100	nA	
		$V_{DS} = 20 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 125°C			50	μΑ	
		$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 175°C			150		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS}$ = 5 V, $V_{GS}$ = 4.5 V	120			А	
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 30 A	0.004			Ω	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125°C	0.007				
	<sup>r</sup> DS(on)	$V_{GS}$ = 4.5 V, $I_{D}$ = 30 A, $T_{J}$ = 175°C		0.010		. 52	
		$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.005			
Forward Transconductancea	9 <sub>fs</sub>	$V_{DS} = 5 V, I_{D} = 30 A$	20			S	
Dynamic <sup>b</sup>				•	•		
Input Capacitance	C <sub>iss</sub>			6000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 20 V, f = 1 MHz		1100			
Reversen Transfer Capacitance	C <sub>rss</sub>			600			
Total Gate Charge <sup>c</sup>	Qg			65	130	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 85 A		13			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			14		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			25	40	ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	$\label{eq:VDD} \begin{array}{l} V_{DD} = 10 \; V,  R_{L} = 0.12 \; \Omega \\ \\ I_{D} \simeq 85 \; A,  V_{GEN} = 4.5 \; V,  R_{G} = 2.5 \; \Omega \end{array}$		120	180		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			80	120		
Fall Time <sup>c</sup>	t <sub>f</sub>			100	150		
Source-Drain Diode Ratings a	nd Characteristic	cs (T <sub>C</sub> = 25°C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>				240	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V		1.2	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, di/dt = 100 A/μs		45	100	ns	



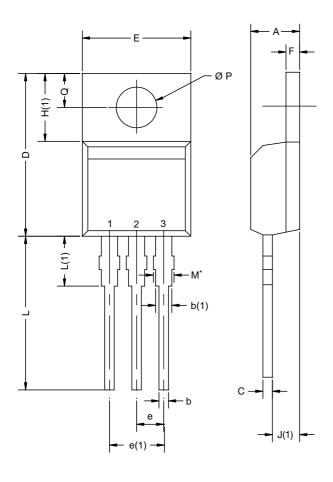








## **TO-220AB**



	MILLIN	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471				

#### Notes

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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